

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>You-Hua Chou</td> <td>02/06/2012</td> </tr> <tr> <td>Chih-Tsung Lee</td> <td>02/06/2012</td> </tr> <tr> <td>Chia-Ho Chen</td> <td>02/06/2012</td> </tr> <tr> <td>Chin-Hsiang Lin</td> <td>02/06/2012</td> </tr> </tbody> </table>		Name	Execution Date	You-Hua Chou	02/06/2012	Chih-Tsung Lee	02/06/2012	Chia-Ho Chen	02/06/2012	Chin-Hsiang Lin	02/06/2012		
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<table border="1"> <tr> <td>Name:</td> <td>Taiwan Semiconductor Manufacturing Co., Ltd.</td> </tr> <tr> <td>Street Address:</td> <td>No. 8, Li-Hsin Rd. 6</td> </tr> <tr> <td>Internal Address:</td> <td>Hsin-Chu Science Park</td> </tr> <tr> <td>City:</td> <td>Hsin-Chu</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> <tr> <td>Postal Code:</td> <td>300-77</td> </tr> </table>		Name:	Taiwan Semiconductor Manufacturing Co., Ltd.	Street Address:	No. 8, Li-Hsin Rd. 6	Internal Address:	Hsin-Chu Science Park	City:	Hsin-Chu	State/Country:	TAIWAN	Postal Code:	300-77
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CORRESPONDENCE DATA													
<p>Fax Number: (216)502-0601</p> <p>Phone: 216-502-0600</p> <p>Email: Docketing@eschweilerlaw.com</p> <p><i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i></p> <p>Correspondent Name: ESCHWEILER & ASSOCIATES, LLC NATIONAL CI</p> <p>Address Line 1: 629 EUCLID AVE., SUITE 1000</p> <p>Address Line 4: CLEVELAND, OHIO 44114</p>													
ATTORNEY DOCKET NUMBER:	TSMCP130US												
NAME OF SUBMITTER:	Thomas G. Eschweiler												

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Total Attachments: 6

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U.S. Patent Appln. No.

Docket No. TSMCP130US

Filing Date:

PATENT ASSIGNMENT

PARTIES TO THE ASSIGNMENT

Assignor(s):

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Hsin-Chu, Taiwan 300-77
Republic of China

AGREEMENT

WHEREAS, ASSIGNOR(S) (listed above) are inventor(s) of an invention entitled

“CVD CONFORMAL VACUUM/PUMPING GUIDING DESIGN” for which:

a non-provisional application for United States Letters Patent:

U.S. Patent Appln. No.

Docket No. TSMCP130US

Filing Date:

☒ was executed on even date preparatory to filing (each inventor should sign this Assignment on the same day as he/she signs the Declaration and Power of Attorney); or

☐ was filed on _____ and accorded U.S. Serial No. _____; or

☐ will be filed without this executed PATENT ASSIGNMENT. ASSIGNOR hereby authorizes and requests ASSIGNEE'S legal representatives, the attorneys associated with Customer No. _____, to insert below in this document this APPLICATION's U.S. Serial Number and filing date, when known:

U.S. Serial No. _____,

filed on _____.

WHEREAS, ASSIGNEE (listed above), a corporation of the Republic of China is desirous of acquiring the entire right, title and interest in and to the invention and in and to any letters patent that may be granted therefore in the United States and in any and all foreign countries;

NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR(S) hereby sell, assign and transfer unto ASSIGNEE its successors and assigns, the entire right, title and interest in and to said invention and improvements, said application and any and all letters patent which may be granted for said invention in the United States of America and its territorial possessions and in any and all foreign countries, and in any and all divisions, reissues, re-examinations and continuations thereof, including the right to file foreign applications directly in the name of ASSIGNEE and to claim priority rights deriving from said United States application to which said foreign applications are entitled by virtue of international convention, treaty or otherwise, said invention, application and all letters patent on said invention to be held and enjoyed by

U.S. Patent Appln. No.

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Filing Date:

ASSIGNEE and its successors and assigns for their use and benefit and of their successors and assigns as fully and entirely as the same would have been held and enjoyed by ASSIGNOR(S) had this assignment, transfer and sale not been made. ASSIGNOR(S) hereby authorize and request the Commissioner of Patents and Trademarks to issue all letters patent on said invention to ASSIGNEE. ASSIGNOR(S) agree to execute all instruments and documents required for the making and prosecution of applications for United States and foreign letters patent on said invention, for litigation regarding said letters patent, or for the purpose of protecting title to said invention or letters patent therefore.

Feb. 6, 2012
Date

You-hua Chou
Name 1st Inventor You-Hua Chou

TSMC Docket No. TSMC2011-1454

U.S. Patent Appln. No.

Docket No. TSMCP130US

Filing Date:

2.6.2012
Date

Chih-Tsung Lee
Name 2nd Inventor Chih-Tsung Lee

TSMC Docket No. TSMC2011-1454

U.S. Patent Appln. No.

Docket No. TSMCP130US

Filing Date:

2012. 2. 6
Date

Chiaho - Chen
Name 3rd Inventor Chia-Ho Chen

TSMC Docket No. TSMC2011-1454

Docket No. TSMCP130US

U.S. Patent Appin. No.

Filing Date:

2012.02.06
Date


Name 4th Inventor Chin-Hsiang Lin